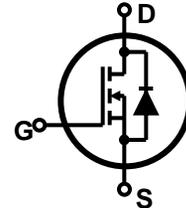
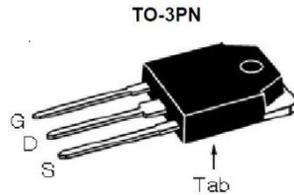


Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- JEDEC Qualification

| | | |
|------------|-------|--------------|
| BV_{DSS} | I_D | $R_{DS(on)}$ |
| 500V | 20A | <0.3Ω |



| Device | Package | Marking | Remark |
|--------------|---------|--------------|--------|
| GP1M020A050N | TO-3PN | GP1M020A050N | RoHS |

Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit | |
|---|----------------|-----------------------|------|------|
| Drain-Source Voltage | V_{DS} | 500 | V | |
| Gate-Source Voltage | V_{GS} | ±30 | V | |
| Continuous Drain Current | I_D | $T_C = 25\text{ °C}$ | 20 | A |
| | | $T_C = 100\text{ °C}$ | 13.1 | A |
| Pulsed Drain Current ^(Note 1) | I_{DM} | 80 | A | |
| Single Pulse Avalanche Energy ^(Note 2) | E_{AS} | 1088 | mJ | |
| Repetitive Avalanche Current ^(Note 1) | I_{AR} | 20 | A | |
| Repetitive Avalanche Energy ^(Note 1) | E_{AR} | 31.2 | mJ | |
| Power Dissipation | P_D | $T_C = 25\text{ °C}$ | 312 | W |
| | | Derate above 25 °C | 2.5 | W/°C |
| Peak Diode Recovery dv/dt ^(Note 3) | dv/dt | 4.5 | V/ns | |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55~150 | °C | |
| Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | T_L | 300 | °C | |

* Limited only by maximum junction temperature

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Maximum Thermal resistance, Junction-to-Case | $R_{\theta JC}$ | 0.4 | °C/W |
| Maximum Thermal resistance, Junction-to-Ambient | $R_{\theta JA}$ | 62.5 | °C/W |

Electrical Characteristics : $T_C=25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Test condition | Min | Typ | Max | Units |
|-------------------------------------|------------|--|-----|-----|------|---------------|
| OFF | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ | 500 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$ | -- | -- | 1 | μA |
| | | $V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$ | -- | -- | 10 | μA |
| Forward Gate-Source Leakage Current | I_{GSSF} | $V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | 100 | nA |
| Reverse Gate-Source Leakage Current | I_{GSSR} | $V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | -100 | nA |

ON

| | | | | | | |
|--|--------------|---|----|------|-----|----------|
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$ | 2 | -- | 4 | V |
| Drain-Source On-Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 10\text{ A}$ | -- | 0.25 | 0.3 | Ω |
| Forward Transconductance ^(Note 4) | g_{FS} | $V_{DS} = 30\text{ V}, I_D = 10\text{ A}$ | -- | 11 | -- | S |

DYNAMIC

| | | | | | | |
|------------------------------|-----------|--|----|------|----|----|
| Input Capacitance | C_{iss} | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$ | -- | 3094 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 296 | -- | pF |
| Reverse Transfer Capacitance | C_{rss} | | -- | 9.2 | -- | pF |

SWITCHING

| | | | | | | |
|---|--------------|---|----|------|----|----|
| Turn-On Delay Time ^(Note 4,5) | $t_{d(on)}$ | $V_{DD} = 250\text{ V}, I_D = 20\text{ A},$ $R_G = 25\ \Omega$ | -- | 78 | -- | ns |
| Turn-On Rise Time ^(Note 4,5) | t_r | | -- | 72 | -- | ns |
| Turn-Off Delay Time ^(Note 4,5) | $t_{d(off)}$ | | -- | 184 | -- | ns |
| Turn-Off Fall Time ^(Note 4,5) | t_f | | -- | 68 | -- | ns |
| Total Gate Charge ^(Note 4,5) | Q_g | $V_{DS} = 400\text{ V}, I_D = 20\text{ A},$ $V_{GS} = 10\text{ V}$ | -- | 54 | -- | nC |
| Gate-Source Charge ^(Note 4,5) | Q_{gs} | | -- | 15 | -- | nC |
| Gate-Drain Charge ^(Note 4,5) | Q_{gd} | | -- | 12.5 | -- | nC |

SOURCE DRAIN DIODE

| | | | | | | |
|---|----------|--|----|-----|-----|---------------|
| Maximum Continuous Drain-Source Diode Forward Current | I_S | --- | -- | -- | 20 | A |
| Maximum Pulsed Drain-Source Diode Forward Current | I_{SM} | --- | -- | -- | 80 | A |
| Drain-Source Diode Forward Voltage | V_{SD} | $V_{GS} = 0\text{ V}, I_S = 20\text{ A}$ | -- | -- | 1.5 | V |
| Reverse Recovery Time ^(Note 4) | t_{rr} | $V_{GS} = 0\text{ V}, I_S = 20\text{ A}$ $di_F / dt = 100\text{ A}/\mu\text{s}$ | -- | 426 | -- | ns |
| Reverse Recovery Charge ^(Note 4) | Q_{rr} | | -- | 6 | -- | μC |

Note :

1. Repeated rating : Pulse width limited by safe operating area
2. $L=4.9\text{mH}, I_{AS} = 20\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega,$ Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 20\text{A}, di/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq BV_{DS},$ Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s},$ Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

